

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK,UL94V-0.
- 1.2 CONTACT: Copper Alloy,GOLD (SEE P/N) PLATED IN CONTACT AREA, 80u" MIN MATTE TIN PLATED IN SOLDER AREA,50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING:3A;
- 2.2 DIELECTRIC WITHSTANDING VOLTAGE: 750V AC/MINUTE.
- 2.3 CONTACT RESISTANCE: 20mΩ MAX.
- 2.4 INSULATION RESISTANCE: 1000MΩ MIN.
- 2.5 OPERATION TEMPERATURE:-40°C TO +105°C.

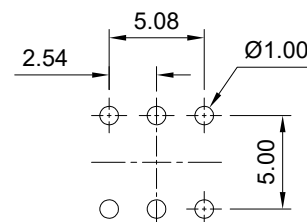
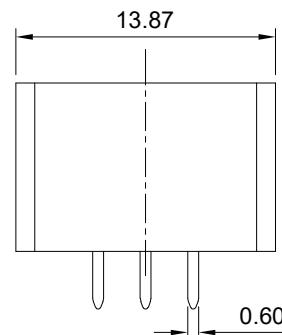
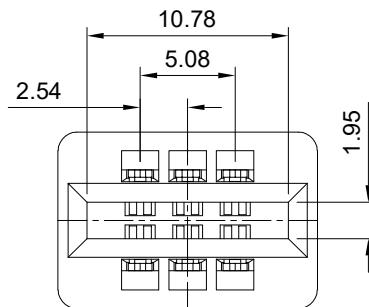
3.ORDER INFORMATION:

61H3- 006 S1 090 C 01

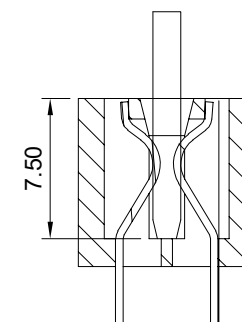
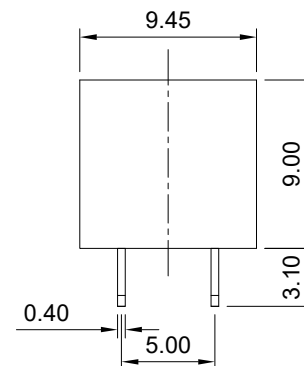
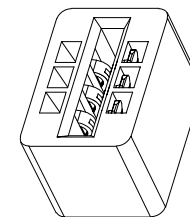
Pin数码
SEE TABLE
006=2X03PIN
008=2*04PIN
.....
100=2X50PIN

端子电镀:
G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
S0=Gold Flash/Tin
S1=1u" Gold/Tin
S2=3u" Gold/Tin
S3=5u" Gold/Tin
S4=10u" Gold/Tin

塑胶高度: 090=9.00mm
包装方式: C=TRAY



建议PCB LAYOUT(顶部)
PCB板公差±0.05



					OPERATION	DRAW	WLY	2020.09.17	SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.			
					X.X ±0.40	DESIGN	Jensen	2020.09.17				
					X.XX ±0.25	CHECK	Jack	2020.09.17				
					X.XXX ±0.15	APPROVE	Andy	2020.09.17				
AO		NEW			Angle ±3°				SHEET	1/1	TITLE:	2.54 SOLT 180° DIP W9.45*H9
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM. TOL	UNIT	mm	SCALE	1:1	PROJ.	DRAW NO.	SP-333